



# AN2169

## Application note

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### Porting an application from the ST10F168 to the ST10F276

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## Introduction

The ST10F276 is a new derivative of the STMicroelectronics ST10 family of 16-bit single-chip CMOS microcontrollers. This document aims to describe the differences between the ST10F168 and ST10F276 and is intended for hardware or software designers who are adapting existing applications based on the ST10F168 to the ST10F276.

This document will present the modified functionalities of the ST10F276, then the new ones before looking at the modified and new registers. For each part, the differences with the ST10F168 that have an impact will be shown and some advice on the way they can be handled will be given.

# Contents

<b>1</b>	<b>Modified features .....</b>	<b>5</b>
1.1	Pin-out .....	5
1.1.1	Pin-out modification summary .....	5
1.1.2	Pin 99 .....	6
1.1.3	Pins 143 & 144 .....	6
1.1.4	Pin 84 .....	6
1.1.5	Pin 56 .....	7
1.2	Maximum CPU frequency .....	7
1.2.1	Hardware impact .....	7
1.2.2	software impact .....	7
1.3	XRAM .....	7
1.3.1	Hardware impact .....	7
1.3.2	Software impact .....	7
1.4	Flash memory .....	8
1.4.1	Hardware impact .....	9
1.4.2	Software impact .....	9
1.5	A/D converter .....	10
1.5.1	Hardware / Software impact: conversion timing control .....	10
1.5.2	Hardware impact .....	10
1.5.3	Software impact .....	11
1.6	PLL and on-chip main oscillator .....	12
<b>2</b>	<b>New functionalities .....</b>	<b>14</b>
2.1	CAN module .....	14
2.1.1	Hardware impact .....	14
2.1.2	Software impact .....	14
2.2	Real time clock .....	14
2.2.1	Hardware impact .....	14
2.2.2	Software impact .....	14
2.3	MAC unit .....	14
2.3.1	Hardware impact .....	14
2.3.2	Software impact .....	14
2.4	Additional X-peripherals .....	15

2.4.1	Hardware impact	15
2.4.2	Software impact	15
2.5	New multiplexer for X-interrupts	15
2.5.1	Hardware impact	16
2.5.2	Software impact	16
2.6	Programmable divider on CLKOUT	17
2.6.1	Hardware impact	18
2.6.2	Software impact	18
<b>3</b>	<b>Modified registers</b>	<b>19</b>
3.1	WDTCON register	19
3.1.1	Hardware impact	20
3.1.2	Software impact	20
3.2	PICON register	20
3.2.1	Hardware impact	21
3.2.2	Software impact	21
3.3	IDCHIP register	21
3.3.1	Hardware Impact	22
3.3.2	Software Impact	22
<b>4</b>	<b>New registers</b>	<b>23</b>
4.1	XPERCON register	23
4.1.1	Hardware impact	24
4.1.2	Software impact	24
4.2	XPEREMU register	24
4.2.1	Hardware Impact	24
4.2.2	Software Impact	25
4.3	EXISEL register	25
4.4	Additional Ports Input Control: XPICON register	26
4.4.1	Hardware impact	26
4.4.2	Software impact	26
4.5	XMISC register	27
4.5.1	Hardware impact	27
4.5.2	Software impact	27
4.6	Emulation dedicated registers	27
4.6.1	Hardware impact	28

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4.6.2	Software impact .....	28
<b>5</b>	<b>Electrical characteristics .....</b>	<b>29</b>
5.1	DC characteristics .....	29
5.1.1	Absolute maximum ratings .....	29
5.1.2	DC characteristics .....	29
<b>6</b>	<b>References .....</b>	<b>31</b>
<b>7</b>	<b>Revision history .....</b>	<b>32</b>

# 1 Modified features

## 1.1 Pin-out

### 1.1.1 Pin-out modification summary

*Table 1* below summarizes the modifications made in the pin-out.

**Table 1. Pin-out modification summary**

Pin no.	ST10F276 pin function	ST10F168 pin function
6 (P6.5)	HOLD External Master Hold request Input SCLK1 SSC1 Master Clock Output SCLK1 SSC1 Slave Clock Input	HOLD External Master Hold request Input
7 (P6.6)	HLDA Hold Acknowledge Output MSTR1 SS1 Master Transmit MSTR1 SS1 Slave Receive O/I	HLDA Hold Acknowledge Output
8 (P6.7)	BREQ Bus Request Output MRST1 SSC1 Master receive MRST1 SSC1 Slave Transmit I/O	BREQ Bus Request Output
9 (P8.0)	CC16IO: CAPCOM2 CC16 Capture-In CC16IO: CAPCOM2 CC16 Compare-Out XPWM0: PWM1 Channel0 Output	CC16IO: CAPCOM2 CC16 Capture-In CC16IO: CAPCOM2 CC16 Compare-Out
12 (P8.3)	CC19IO: CAPCOM2 CC19 Capture-In CC19IO: CAPCOM2 CC19 Compare-Out XPWM3: PWM1Channel3 Output	CC19IO: CAPCOM2 CC19 Capture-In CC19IO: CAPCOM2 CC19 Compare-Out
15(P8.6)	CC22IO: CAPCOM2 CC22 Capture-In CC22IO: CAPCOM2 CC22 Compare-Out RXD1: ASC1 Data Input(Asynch) or I/O(Synch)	CC22IO: CAPCOM2 CC22 Capture-In CC22IO: CAPCOM2 CC22 Compare-Out
16(P8.7)	CC23IO: CAPCOM2 CC23 Capture-In CC23IO: CAPCOM2 CC23 Compare-Out TXD1: ASC1Clock/Data output(Asyn/Syn)	CC23IO: CAPCOM2 CC23 Capture-In CC23IO: CAPCOM2 CC23 Compare-Out
89 (P4.4)	A20 segment address line CAN2_RxD CAN2 Receive Data Input SCL I2C Interface Serial Clock	A20 segment address line
90 (P4.5)	A21 segment address line CAN1_RxD CAN1 Receive Data Input CAN2_RXD CAN2 Receive Data Input	A21 segment address line CAN_RxD CAN Receive Data Input
91(P4.6)	A22 segment address line CAN1_TxD CAN1 TransmitData Output CAN2_TXD CAN2 TransmitData Output	A22 segment address line CAN_TxD CAN TransmitData Output
92 (P4.7)	A23 segment address line CAN2_TxD CAN2 TransmitData Output SDA I2C Interface Serial Data	A23 segment address line
99	$\overline{EA}$ & $V_{STBY}$	$\overline{EA}$
143	XTAL3	$V_{ss}$

Pin no.	ST10F276 pin function	ST10F168 pin function
144	XTAL4	V <sub>DD</sub> Digital supply voltage
84	RPD	V <sub>pp</sub> / RPD
56	V18 1.8v decoupling pin	V <sub>DD</sub> digital supply voltage

### 1.1.2 Pin 99

On the ST10F168, pin 99 is  $\overline{EA}$  and used upon reset to select the start from internal flash or external memory.

Now, on the ST10F276, it has an the additional function of providing the 5V power supply to the device in standby mode (new power saving mode) and is therefore named  $\overline{EA}$  - V<sub>STBY</sub>.

#### Hardware impact

For an application not using the Stand by mode, no change is required on the PCB. However, for the application to use it , the  $\overline{EA}$  - V<sub>STBY</sub> pin must be separated from the common 5v and have a specific supply path.

#### Software impact

None.

### 1.1.3 Pins 143 & 144

These pins were a V<sub>ss</sub>-V<sub>DD</sub> pair in the ST10F168. Now, on the ST10F276, they are used as XTAL3-XTAL4 pair for connection to an optional 32Khz crystal to clock the device during power-down.

#### Hardware impact

PCB must be redesigned. In case the optional 32Khz is not used, XTAL3 must be linked to ground as it was in the ST10F168 but XTAL4 shall be left open.

#### Software impact

In case the optional 32Khz is not used, the bit OFF32 of the RTCCON register shall be set. Prior to setting the OFF32 bit in RTCCON register, the RTC must be enabled by setting RTCEN, bit 4 of XPERCON, and XPEN, bit3 of SYSCON.

### 1.1.4 Pin 84

This pin was named V<sub>pp</sub>/RPD on the ST10F168 and was the 12v input pin Flash programming. In the ST10F276, it is now only used as RPD.

#### Hardware impact

This pin is no longer designed to accept 12V inputs. Its ratings are the same as any other pin: - 0.5V to V<sub>DD</sub> + 0.5V.

#### Software impact

None.

### 1.1.5 Pin 56

For the ST10F168, this is  $V_{DD}$  pin connected to 5Volts.

For the ST10F276, it is a 1.8V decoupling pin and named V18. A decoupling capacitor must be connected between this pin and the nearest  $V_{SS}$  pin.

#### Hardware impact

The application board should be re-designed in order to introduce the decoupling capacitor.

#### Software impact

None

## 1.2 Maximum CPU frequency

	ST10F168	ST10F276
Maximum CPU Frequency (MHz)	25	64

### 1.2.1 Hardware impact

None.

### 1.2.2 software impact

None.

## 1.3 XRAM

The ST10F168 has only 6Kbytes of extension RAM while the ST10F276 has 66Kbytes.

The XRAM address range in the ST10F168 is 00'D000h-00'E7FFh and is enabled if XPEN (bit 2 of SYSCON register) is set.

The XRAM of the ST10F276 is divided into 2 ranges named XRAM1 of 2Kbytes and XRAM2 of 64 Kbytes:

- The XRAM1 address range is 00'E000h - 00'E7FFh if enabled (XPEN set -bit 2 of SYSCON register and XRAM1EN set -bit 2 of XPERCON register).
- The XRAM2 address range is 0F'0000h - 0F'FFFFh if enabled (XPEN set -bit 2 of SYSCON register and XRAM2EN set -bit 3 of XPERCON register).

### 1.3.1 Hardware impact

None

### 1.3.2 Software impact

The memory mapping of the application will be impacted by the difference in XRAM size and by the location of XRAM2 in the segment 15 while in the ST10F168, the whole XRAM is in page 3 of segment 0.

## Variables and PEC transfers

For architecture reasons, the PEC destination and source pointers must be in the segment 0. Therefore all RAM variables and arrays that will be PEC addressed must be located within either the DPRAM (00'F600h - 00'FDFFh) or the XRAM1 (00'E000h - 00'E7FFh).

## About Toolchain memory model

A change in the Toolchain configuration will be needed to take into account the XRAM2 new location. In the ST10F168, all the XRAM is in page 3 and is then automatically addressed using DPP3 that points to the page 3 (in order to access the DPRAM and the SFR/ESFR). For the ST10F276, it will be necessary to dedicate a DPP to access some of the XRAM2.

Example for ST10F276 in case of Small Memory Model with Tasking toolchain:

The Small memory model allows to have a total code size up to 16M, up to 64K of fast accessible 'normal user data' in three different memory configurations and the possibility to access far/huge data, if more than 64K of data is needed.

The three memory configurations possible for this 64K of 'normal user data' are:

- **Default**  
The four DPP registers are assumed to contain their system startup value (0-3), providing one linear data area of 64K in the first segment (00'0000h - 00'FFFFh).
- **Addresses Linear**  
DPP3 contains page number 3, allowing access to SYSTEM (extended) SFR registers and bit addressable memory. DPP0 - DPP2 provide a linear data area of 48K anywhere in memory.
- **Paged**  
DPP3 contains page number 3, allowing access to SYSTEM (extended) SFR registers and bit addressable memory. DPP0, DPP1 and DPP2 contain the page number of a data area of 16K anywhere in memory.

The Default configuration can no longer be used. The other configurations offer the following possibilities:

- with Addresses Linear configuration nearly all the XRAM2 block is covered with DPPs but then accesses to constants must be made via EXTP instructions
- Paged configuration allows to assign up to two DPPs to XRAM2 and one DPP for constants.

## 1.4 Flash memory

**Table 2. Flash Memories key characteristics**

	ST10F168	ST10F276
Flash Size	256K Bytes	832K Bytes
Flash Organization	4 banks	4 banks, 17 blocks
Programming voltage	12V	5 Volts



	ST10F168	ST10F276
Programming method	STEAK TM	Write/Erase Controller
Program/Erase cycles	10 Kcycles, 20 years data retention	100 Kcycles, 20 years data retention

### 1.4.1 Hardware impact

The 12 volts input on pin 84 is no longer needed.

### 1.4.2 Software impact

The mapping of the application and the programming and erasing routines are impacted.

**Figure 1. ST10F168 & ST10 F276 Flash Memories' Mapping**

Segment number	ST10F168 mapping		ST10F276 Mapping	
14			0E'0000 - 0E'FFFF	Reserved for Flash registers
13			0D'0000 - 0D'FFFF	B3F1: 64KB
12			0C'0000 - 0C'FFFF	B3F0 : 64KB
11			0B'0000 - 0B'FFFF	B2F2: 64KB
10			0A'0000 - 0A'FFFF	B2F1 : 64KB
9			09'0000 - 09'FFFF	B2F0 : 64KB
8			08'0000 - 08'FFFF	B1F1 : 64KB
7			07'0000 - 07'FFFF	B1F0 : 64KB
6			06'0000 - 06'FFFF	B0F9 : 64KB
5			05'0000 - 05'FFFF	B0F8: 64KB
4	03'8000 - 04'FFFF	Bank 3 : 96 Kbytes	04'0000 - 04'FFFF	B0F7: 64KB
3	02'0000 - 03'7FFF	Bank 2 : 96 Kbytes	03'0000 - 03'FFFF	B0F6: 64KB
2	01'8000 - 01'FFFF	Bank 1 H : 32 Kbytes	02'0000 - 02'FFFF	B0F5: 64KB
1	01'4000 - 01'7FFF	Alternate Flash Area	01'8000 - 01'FFFF	B0F4: 32KB
	01'0000 - 01'3FFF	Alternate Flash Area	01'0000 - 01'7FFF	Alternate Flash Area
0	00'8000 - 00'FFFF	External memory+IRAM	00'8000 - 00'FFFF	External memory + IRAM
	00'4000 - 00'7FFF	Bank 1L : 16 Kbytes	00'4000 - 00'7FFF	B0F2:8KB & B0F3: 8KB
	00'0000 - 00'3FFF	Bank 0 : 16 Kbytes	00'2000 - 00'3FFF	B0F1:8KB
			00'0000 - 00'1FFF	B0F0:8KB

**Note:** On the ST10F168, Bank 0 and Bank 1L may be remapped from segment 0 to segment 1 by setting `SYSCON.ROMS1`.

On the ST10F276, sectors in segment 0 may be remapped to segment 1 by setting `SYSCON.ROMS1`.

## 1.5 A/D converter

The Analog Digital converter has been re-designed between the ST10F168 and ST10F276. The ST10F276 still provides an Analog / Digital Converter with 10-bit resolution and a sample & hold circuit on-chip.

### 1.5.1 Hardware / Software impact: conversion timing control

The A/D converter is not fully compatible versus ST10F168 (timing and programming model). As for the ST10F168, the sample time ( for loading the capacitors) and the conversion time are programmable and can be adjusted to the external circuitry. The total conversion time is compatible with the formula used for ST10F168, while the meaning of the bit fields ADCTC and ADSTC is no longer compatible.

**Table 3. ST10F276 Conversion timing table**

ADCTC	ADSTC	Sample	Comparison	Extra	Total Conversion
00	00	TCL * 120	TCL * 240	TCL * 28	TCL * 388
00	01	TCL * 140	TCL * 280	TCL * 16	TCL * 436
00	10	TCL * 200	TCL * 280	TCL * 52	TCL * 532
00	11	TCL * 400	TCL * 280	TCL * 44	TCL * 724
11	00	TCL * 240	TCL * 120	TCL * 52	TCL * 772
11	01	TCL * 280	TCL * 560	TCL * 28	TCL * 868
11	10	TCL * 400	TCL * 560	TCL * 100	TCL * 1060
11	11	TCL * 800	TCL * 560	TCL * 52	TCL * 1444
10	00	TCL * 480	TCL * 960	TCL * 100	TCL * 1540
10	01	TCL * 560	TCL * 1120	TCL * 52	TCL * 1732
10	10	TCL * 800	TCL * 1120	TCL * 196	TCL * 2116
10	11	TCL * 1600	TCL * 1120	TCL * 164	TCL * 2884

### 1.5.2 Hardware impact

**Table 4. ADC differences**

Parameter	Symbol	Limit values for ST10F168		Limit values for ST10F276		Unit
		min.	max.	min.	max.	
<b>Analog Reference voltage</b>	$V_{AREF}$	4.0	$V_{DD} + 0.1$	4.5	$V_{DD} + 0.1$	V
<b>Reference supply current</b> running mode power-down mode	$I_{AREF}$	- -		- -	5000 1	$\mu A$

Parameter	Symbol	Limit values for ST10F168		Limit values for ST10F276		Unit
		min.	max.	min.	max.	
<b>ADC Input capacitance</b>	$C_{AIN}$				$C_{P1} + C_{P2} + C_S$	pF
Not sampling P5		-	33	-	7	
Sampling P5		-	33	-	10.5	
Not sampling P1		-	-	-	9	
Sampling P1		-	-	-	12.5	
<b>Sample time</b>	$t_S$	48 TCL	1536 TCL	120 TCL	1600 TCL	us
<b>Total Unadjusted Error</b>	TUE					LSB
Port5				-2.0	+2.0	
Port1 - No overload		-2.0	+2.0	-5.0	+5.0	
Port1 - Overload				+7.0	+7.0	
<b>Differential Nonlinearity</b>	DNL			-1	+1	LSB
<b>Integral Nonlinearity</b>	INL			-1.5	+1.5	LSB
<b>Offset Error</b>	OFS			-1.5	+1.5	LSB

### 1.5.3 Software impact

#### Self-calibration and ADC initialization routine

An automatic self-calibration adjusts the ADC module to process parameter variations at each reset event. After reset, the busy flag (read-only) ADBSY is set because the self-calibration is ongoing. The duration of self-calibration depends on the CPU clock: it takes up to  $40.629 \pm 1$  clock pulses. The user shall poll this bit to know when the self-calibration is done and then initialize the ADC module.

This self-calibration is seen by the ST10F276 as a conversion and thus bit ADCIR is set. The software should perform a dummy read of the ADDAT register and clear the ADCIR and ADCEIR flag before configuring the ADC module and starting the first conversion.

#### New bit ADOFF, bit 6 of ADCON register

##### ADCON (FFA0h / A0h)

SFR

Reset Value: 0000h

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ADCTC	ADSTC	ADCTC	ADCIN	ADWR	ADBSY	ADST	ADOFF	ADM	ADCH						
RW	RW	RW	RW	RW	R	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW

Bit	Function	Comment
6	<b>ADOFF: ADC Disable</b> 0: Analog circuitry of A/D converter is on 1: Analog circuitry of A/D converter is turned off (no consumption)	New bit only for the ST10F276. Reserved for the ST10F168.

The bit 6 of ADCON register, reserved in the previous ST10 devices, has now the function of enabling or disabling the ADC. By default this bit is cleared and the ST10F276 is compatible with the ST10F168.

### Additional analog channels on Port1

A new multiplexer selects between up to 16 or 8 analog input channels (alternate functions of Port 5 and Port1). The selection of the Port1 or Port5 as input of the ADC is made via bit ADCMUX, bit 0 of XMISC register.

### XMISC (EB46h)

XREG

Reset Value: --00h

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	-	-	-	-	-	VREG OFF	CANC K2	CANP AR	ADCM UX
												rW	rW	rW	rW

Bit	Function
0	<b>ADCMUX</b> 0: default configuration, analog inputs on port P5.y can be converted 1: analog inputs on port P1.z can be converted, only 8 channel can be managed

By default the multiplexer selects the Port5, so there is no impact on the software with regard to a ST10F168 implementation.

## 1.6 PLL and on-chip main oscillator

In order to reach the new frequency range, the PLL multiplication factors have been changed.

**Table 5. ST10F168 vs ST10F276 PLL ratio**

P0.15-13 (P0H.7-5)	ST10F168	ST10F276	ST10F276		ST10F276
	PLL factor $f_{CPU} = f_{XTAL} * F$	PLL factor $f_{CPU} = f_{XTAL} * F$	Input Frequency Range (MHz)		Notes
			Low Power Oscillator	Wide Swing Oscillator	
1 1 1	$F_{XTAL} * 4$	$F_{XTAL} * 4$	4 to 8	4 to 8	Default configuration
1 1 0	$F_{XTAL} * 3$	$F_{XTAL} * 3$	5.3 to 8	5.3 to 10.6	
1 0 1	$F_{XTAL} * 2$	$F_{XTAL} * 8$	4 to 8	4 to 8	
1 0 0	$F_{XTAL} * 5$	$F_{XTAL} * 5$	6.4 to 8	6.4 to 12	
0 1 1	$F_{XTAL} * 1$	$F_{XTAL} * 1$	1 to 64	1 to 64	Direct Drive
0 1 0	$F_{XTAL} * 1.5$	$F_{XTAL} * 10$	4 to 6.4	4 to 6.4	

P0.15-13 (P0H.7-5)	ST10F168	ST10F276	ST10F276		ST10F276
	PLL factor $f_{CPU} = f_{XTAL} * F$	PLL factor $f_{CPU} = f_{XTAL} * F$	Input Frequency Range (MHz)		
			Low Power Oscillator	Wide Swing Oscillator	Notes
0 0 1	$F_{XTAL} / 2$	$F_{XTAL} / 2$	4 to 8	4 to 12	CPU clock via pre-scaler
0 0 0	$F_{XTAL} * 2.5$	$F_{XTAL} * 16$	4	4	

## 2 New functionalities

### 2.1 CAN module

The ST10F168 has only one CAN module of the B-CAN type.

The ST10F276 has two CAN modules of the C-CAN type.

The C-CAN cells provide additional Message Objects and new functionalities like Time Triggered Protocol capability. The main difference is that the Message Objects are no longer directly accessed as memory but are available through a Message Interface. This changes the programming model of the modules.

#### 2.1.1 Hardware impact

None.

#### 2.1.2 Software impact

Re-write the CAN Drivers

### 2.2 Real time clock

This is a new functionality of the ST10F276.

The Real Time Clock is an independent timer. Its clock is directly derived from the clock oscillator so that it can keep on running even in idle or power down mode (if enabled).

#### 2.2.1 Hardware impact

None

#### 2.2.2 Software impact

None. By default, this peripheral is disabled.

### 2.3 MAC unit

This Multiply and Accumulate Unit is a feature added on the ST10F276.

#### 2.3.1 Hardware impact

None

#### 2.3.2 Software impact

None

## 2.4 Additional X-peripherals

Some peripherals have been added on the ST10F271-B. They are mapped on the X-Bus and are linked to additional alternate functions of some ports of the ST10F271-B.

The additional X-Peripherals are the following:

- An additional SSC called XSSC.
- An additional ASC called XASC.
- An additional 4-channel PWM called XPWM .
- An I2C interface
- An additional C-CAN Interface

*Note: Some restrictions and functional differences between the original peripherals and XASC, XSSC and XPWM exist. Those differences impact interrupts management, related IO configuration and peripherals activation.*

### 2.4.1 Hardware impact

None if the additional peripherals are not used.

### 2.4.2 Software impact

None if the additional peripherals are not used. As they are X-peripherals, they can be enabled / disabled via the XPERCON and the SYSCON registers.

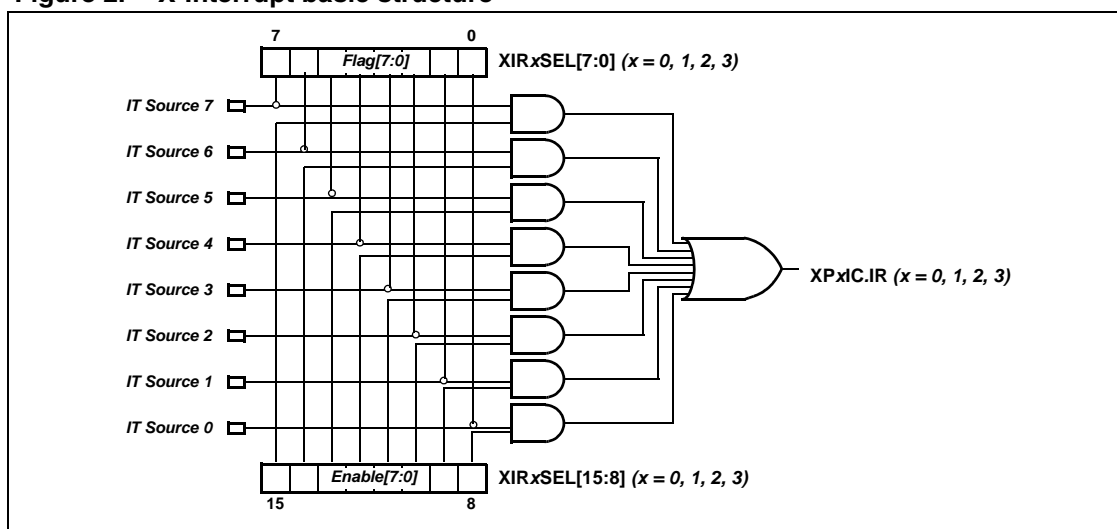
## 2.5 New multiplexer for X-interrupts

The limited number of X-Bus interrupt lines of the present ST10 architecture, imposes some constraints on the implementation of the new functionalities. In particular, the additional X-Peripherals XSSC, XASC, XI2C and XPWM need some resources to implement interrupt and PEC transfer. For this reason, a complex but very flexible multiplexed structure for the interrupt is proposed. In next figure, the principle is represented through a simple diagram, which shows the basic structure replicated for each of the four X-interrupt vectors (XP0INT, XP1INT, XP2INT and XP3INT).

It is based on a new 16-bit register XIRxSEL (x=0,1,2,3), divided in two portions:

- Byte High (XIRxSEL[15:8]) Interrupt Enable bits
- Byte Low (XIRxSEL[7:0]) Interrupt Flag bits

When different sources submit an interrupt request, the enable bits (Byte High of XIRxSEL register) define a mask which controls which sources will be associated with the unique available vector. If more than one source is enabled to issue the request, the service routine will have to take care to identify the real event to be serviced. This can easily be done by checking the flag bits (Byte Low of XIRxSEL register). Note that the flag bit can provide information about events which are not currently serviced by the interrupt controller (when masked through the enable bits), allowing an effective software management also in absence of the possibility to serve the related interrupt request: a period polling of the flag bits may be implemented inside the user application.

**Figure 2. X-Interrupt basic structure****Table 6. X-Interrupt detailed mapping**

	XP0INT	XP1INT	XP2INT	XP3INT
CAN1 Interrupt	X			X
CAN2 Interrupt		X		X
I2C Receive	X	X	X	
I2C Transmit	X	X	X	
I2C Error				X
SSC1 Receive	X	X	X	
SSC1 Transmit	X	X	X	
SSC1 Error				X
ASC1 Receive	X	X	X	
ASC1 Transmit	X	X	X	
ASC1 Transmit Buffer	X	X	X	
ASC1 Error				X
PLL Unlock / OWD				X
PWM1 Channel 3...0			X	X

### 2.5.1 Hardware impact

None.

### 2.5.2 Software impact

The XIRxSEL registers must be configured.

If none of the new X-Peripherals are used, i.e. only the X-Peripherals that were already present on the ST10F168 are used, the following configuration can be used:



- XIR0SEL = 0x0100, only CAN1 interrupt is enabled and will generate an interrupt to the ST10 through XP0IC
- XIR2SEL = 0x0, not used
- XIR3SEL = 0x2000, only PLL unlock interrupt is enabled and will generate an interrupt to the ST10 through XP3IC.

Then, in the interrupt routines associated to the XPxIC, the respective flag in XIRxSEL register must be cleared. Since the XIRxSEL registers are not bit addressable, a pair of registers (a pair for each XIRxSEL) is provided to allow setting and clearing the bits of XIRxSEL without risking to overwrite requests coming after reading the register and before writing it. Therefore the following registers must be written to clear the flags:

- in the CAN1 interrupt routine, XIR0CLR (@ EB14h) = 0x0001
- in the PLL unlock interrupt routine, XIR3CLR (@ EB44h) = 0x0020

### Additional information on the X-Interrupt multiplexer structure

Figure 2 shows that the X-Interrupt sources are connected to the interrupt request flag of the XIRxSEL registers and to the XPxIR request flag via an AND gate with the enable bit. This AND gate is activated by a transition on the Interrupt source line and not by the latched value in the XIRxSEL register meaning:

- A transition on the IT source line will generate an interrupt to the ST10 core if the source is enabled.
- Writing to an interrupt request flag in a XIRxSEL register will not generate an interrupt to the ST10 core.

**Example:** If XIR0SEL = 0x0100: CAN1 interrupt enabled on XP0IC interrupt

To trigger by software the CAN1 interrupt routine with XP0IC register, the following code must be used:

```
XIR0SET = 0x0001; /* Set CAN1 interrupt request Flag in XIR0SEL
register */
XP0IC = XP0IC | 0x0080; /* Set XP0IR flag and generate an interrupt
routine to the ST10 */
```

Executing only the first line will only set the flag in the XIR0SEL register but will not be seen by the AND gate and can not set the XP0IR flag.

## 2.6 Programmable divider on CLKOUT

A specific register mapped on the XBUS allows to choose the division factor on the CLKOUT signal (P3.15).

### XCLKOUTDIV (E902h)

XBUS

Reset Value: --00h

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	-	DIV							
								rw	rw	rw	rw	rw	rw	rw	rw

Bit	Function
7:0	<b>DIV</b> $F_{clkout} = F_{cpu} / (DIV + 1)$

### 2.6.1 Hardware impact

None.

### 2.6.2 Software impact

None if only CLOCKOUT is needed.

When CLKOUT function is enabled by setting the bit CLKEN of register SYSCON, by default the CPU clock is output on P3.15. To have access to XCLKOUTDIV register, and thus program the clock pre-scaling factor, the bit XMISCEN of XPERCON and XPEN of SYSCON registers must be set.

## 3 Modified registers

### 3.1 WDTCON register

Some bits have been added for the ST10F276. Each of the different reset sources is indicated in the WDTCON register of the ST10F276. The indicated bits are cleared with the EINIT instruction. It is thus possible to identify the reset during the initialization phase.

#### ST10F168: WDTCON (FFAEh / D7h)

SFR

Reset Value: --05h

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
WDTREL								-	-	-				WDTR	WDTIN
RW	RW	RW	RW	RW	RW	RW	RW	-	-	-				R	RW

#### ST10F276: WDTCON (FFAEh / D7h)

SFR

Reset Value: -005h

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
WDTREL										PONR	LHWR	SHWR	SWR	WDTR	WDTIN
RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	HR	HR	HR	HR	HR	RW

Bit	Function
15:8	<b>WDTREL:</b> Watchdog Timer Reload Value (for the high byte)
5 (ST10F276)	<b>PONR:</b> Power-on (Asynchronous) Reset Indication Flag Set by the Input RSTIN if a power-On condition has been detected. Cleared by the EINIT instruction
4 (ST10F276)	<b>LHWR:</b> Long Hardware Reset indication Flag Set by the input RSTIN Cleared by the EINIT instruction
3 (ST10F276)	<b>SHWR:</b> Short Hardware Reset indication Flag Set by the input RSTIN Cleared by EINIT instruction
2 (ST10F276)	<b>SWR:</b> Software Reset Indication Flag Set by the SRST execution Cleared by the EINIT instruction

Bit	Function
1	<b>WDTR: Watchdog Timer Reset Indication Flag</b> Set by the watchdog timer on an overflow. Cleared by a hardware reset or by the SRVWDT instruction.
0	<b>WD TIN: Watchdog Timer Input Frequency Selection</b> 0: Input frequency is Fcpu /2 1: Input frequency is Fcpu /128

Note: 1 More than one RESET indication flag may be set. After EINIT, all flags are cleared.  
2 Power-on is detected when a rising edge from VDD=0 V to VDD<2.0 V is recognized.

### 3.1.1 Hardware impact

None.

### 3.1.2 Software impact

None if the ST10F168 software was masking the non-implemented bits.

## 3.2 PICON register

Some bits have been added, and some suppressed in this register for the ST10F276.

The port Input Control register PICON is used to select between TTL and CMOS-like input thresholds.

The CMOS-like input thresholds are defined above the TTL levels and feature a defined hysteresis to prevent the inputs from toggling while the respective input signal level is near the thresholds.

On the ST10F168, this functionality is available for pins of port 2, port3, port7 and port8 and the hysteresis level is 300 mV for CMOS levels.

In the ST10F276, this functionality has been added for the pins of port 4 and port 6.

Moreover the default hysteresis is now 500 mV for TTL levels and is 800 mV for CMOS levels.

#### ST10F168: PICON (F1C4h /E2h)

ESFR

Reset Value: 0000h

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
P8LOUT	P7LOUT	-		P3HOUT	P3LOUT	P2HOUT	P2LOUT	P8LIN	P7LIN			P3HIN	P3LIN	P2HIN	P2LIN
RW	RW			RW	RW	RW	RW	RW	RW			RW	RW	RW	RW

#### ST10F276: PICON (F1C4h / E2h)

ESFR

Reset Value: 0000h

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	-	P8LIN	P7LIN	P6LIN	P4LIN	P3HIN	P3LIN	P2HIN	P2LIN
								RW	RW	RW	RW	RW	RW	RW	RW

Bit Name	Function	
<b>PxLIN</b>	<i>Port x Low Byte Input Level Selection</i> 0: Pins Px.7..0 switch on standard TTL input levels 1: Pins Px.7..0 switch on CMOS input levels	
<b>PxHIN</b>	<i>Port x High Byte Input Level Selection</i> 0: Pins Px.15..8 switch on standard TTL input levels 1: Pins Px.15..8 switch on CMOS input levels	
<b>PxLOUT</b>	<i>Port x Low Byte Output Driver Characteristic selection</i> 0: Pins Px.7...0 output driver strength is reduced after reaching VOL or VOH 1: Pins Px.7...0 output drive is not reduced after reaching VOL or VOH	Only for ST10F168
<b>PxHOUT</b>	<i>Port x High Byte Output Driver Characteristic selection</i> 0: Pins Px.15...8 output driver strength is reduced after reaching VOL or VOH 1: Pins Px.15...8 output drive is not reduced after reaching VOL or VOH	Only for ST10F168

### 3.2.1 Hardware impact

The CMOS levels of the 2 devices are slightly different, therefore the circuitry must be checked to verify that the new levels can still match the requirements.

### 3.2.2 Software impact

The high byte of the PICON register is reserved on the ST10F276. Check that the ST10F168 was not writing in bits P4LIN and P6LIN of PICON which are no longer reserved on the ST10F276.

## 3.3 IDCHIP register

A new field has been added inside the IDCHIP register to distinguish the different peripheral options.

### ST10F168: IDCHIP (F07Ch)

ESFR

Reset Value: 10DXh

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
CHIPID												REVID			
R	R	R	R	R	R	R	R	R	R	R	R	R	R	R	R

**ST10F276: IDCHIP (F07Ch)**

ESFR

Reset Value: 114Xh

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
PCONF		CHIPID										REVID			
R	R	R	R	R	R	R	R	R	R	R	R	R	R	R	R

Bit Name	Function
<b>REVID</b>	<i>ST10 Module Revision Identifier (Full Mask Set revision)</i> 01h: Rev. A (First main revision) 02h: Rev. B (Second main revision) : 0Fh: Rev. P
<b>CHIPID</b>	<i>ST10 Module Identifier</i> 0A8: ST10F168 identifier (168d = 0A8h) 114h: ST10F276 identifier (276d = 114h)
<b>PCONF</b>	<i>Peripheral Configuration</i> 00: (E) Enhanced (ST10F276) 01: (B) Basic 10: (D) Dedicated 11: <i>reserved</i>

**3.3.1 Hardware Impact**

None.

**3.3.2 Software Impact**

None.

## 4 New registers

This section presents new registers that have to be considered when porting an application running on the ST10F168 onto the ST10F276.

### 4.1 XPERCON register

The ST10F276 has a new register named XPERCON that allows the XBUS peripherals to be separately selected for being visible to the user by means of corresponding bits. If not selected (not activated with a bit of XPERCON) before the XPEN bit in SYSCON is set, the corresponding address space, port pins and interrupts are not occupied by the peripheral, and thus this peripheral is not visible and not available.

#### ST10F276: XPERCON (F024h / 12h)

SFR

Reset Value: -005h

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
-	-	-	-	-	XMISC EN	XI2C EN	XSSC EN	XASC EN	XPWM EN	XFLASH EN	RTC EN	XRAM2 EN	XRAM1 EN	CAN2 EN	CAN1 EN
					RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW

Bit	Function
15:11	Reserved
10	<b>XMISCEN:</b> <i>XBUS Additional Features Enable Bit</i> 0: Accesses to the Additional Miscellaneous Features is disabled. 1: The Additional Features are enabled and can be accessed.
9	<b>XI2CEN:</b> <i>XI 2 C Enable Bit</i> 0: Accesses to the on-chip XI 2 C are disabled, external access performed. 1: The on-chip XI 2 C is enabled and can be accessed.
8	<b>XSSCEN:</b> <i>XSSC Enable Bit</i> 0: Accesses to the on-chip XSSC are disabled, external access performed. 1: The on-chip XSSC is enabled and can be accessed.
7	<b>XASCEN:</b> <i>XASC Enable Bit</i> 0: Accesses to the on-chip XASC are disabled, external access performed. 1: The on-chip XASC is enabled and can be accessed.
6	<b>XPWMEN:</b> <i>XPWM Enable</i> 0: Accesses to the on-chip XPWM module are disabled, external access performed. 1: The on-chip XPWM module is enabled and can be accessed.
5	<b>XXFLASHEN:</b> <i>FLASH Enable Bit</i> 0: Accesses to the on-chip XFLASH are disabled, external access performed. 1: The on-chip XFLASH is enabled and can be accessed.

Bit	Function
4	<b>RTCEN:</b> <i>RTC Enable Bit</i> 0: Accesses to the on-chip Real Time Clock are disabled, external access performed. 1: The on-chip Real Time Clock is enabled and can be accessed.
3	<b>XRAM2EN:</b> <i>XRAM2 Enable Bit</i> 0: Accesses to the on-chip XRAM2 block are disabled, external access performed. 1: The on-chip XRAM2 is enabled and can be accessed.
2	<b>XRAM1EN:</b> <i>XRAM1 Enable Bit</i> 0: Accesses to the on-chip XRAM1 block are disabled, external access performed. 1: The on-chip XRAM1 is enabled and can be accessed.
1	<b>CAN2EN:</b> <i>CAN2 Enable Bit</i> 0: Accesses to the CAN2 XPeripheral and its functions are disabled (P4.4 and P4.7 pins can be used as general purpose IOs) 1: The CAN2 X-Peripheral is enabled and can be accessed.
0	<b>CAN1EN:</b> <i>CAN1 Enable Bit</i> 0: Accesses to the CAN1 XPeripheral and its functions are disabled (P4.5 and P4.6 pins can be used as general purpose IOs) 1: The CAN1 X-Peripheral is enabled and can be accessed.

#### 4.1.1 Hardware impact

None.

#### 4.1.2 Software impact

The value has to be changed from its default reset one to match XRAM size compatibility. Refer to XRAM section for more details.

### 4.2 XPEREMU register

This register has been added as a write-only register.

#### ST10F276: XPEREMU (EB7Eh)

XREG

Reset Value: XXXXh

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
-	-	-	-	-	XMISC EN	XI2C EN	XSSC EN	XASC EN	XPWM EN	XFLASH EN	XRTC EN	XRAM2 EN	XRAM1 EN	CAN2 EN	CAN1 EN
-	-	-	-	-	W	W	W	W	W	W	W	W	W	W	W

The bit description is exactly the same as XPERCON.

#### 4.2.1 Hardware Impact

None.



### 4.2.2 Software Impact

Once the XPEN bit of SYSCON register is set and at least one of the X-peripherals (except memories) is activated, the register XPEREMU must be written with the same content of XPERCON: this is mandatory in order to allow a correct emulation of the new set of features introduced on X-BUS for the new ST10 generation. The following instructions must be added inside the initialization routine:

```
if (SYSCON.XPEN && (XPERCON & 0x07D3))
then { XPEREMU = XPERCON }
```

Of course, XPEREMU must be programmed after XPERCON and after SYSCON, in such a way the final configuration for X-Peripherals is stored in XPEREMU and used for the emulation hardware setup.

## 4.3 EXISEL register

This register, standing for External Interrupt source selection, has been added in the ST10F276.

The purpose of this new register is to select the interrupt sources of the fast external interrupts among the other peripherals. For example, the CANy controller receive signal (CANy\_RxD) can be used to interrupt the system(y=1,2).

### ST10F276: EXISEL (F1DAh / EDh)

SFR

Reset Value: -005h

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
EXI7SS	EXI6SS	EXI5SS	EXI4SS	EXI3SS	EXI2SS	EXI1SS	EXI0SS								
RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW

Bit name	Function
EXIxSS	<p>External Interrupt x source Selection (x=7..0)</p> <p>00: Input from associated Port 2 pin.</p> <p>01: Input from "alternate source".</p> <p>10: Input from associated Port 2 pin logically ORed with "alternate source".</p> <p>11: Input from associated Port 2 pin logically ANDed with "alternate source".</p>

EXIxSS	Port 2 pin	Alternate source	
0	P2.8	CAN1_RxD	P4.5
1	P2.9	CAN2_RxD / SCL	P4.4
2	P2.10	RTC_secIT	Internal MUX
3	P2.11	RTC_alarmIT	Internal MUX
4..7	P2.12..P2.15	Not used (zero)	-

## 4.4 Additional Ports Input Control: XPICON register

The possibility to select between TTL and CMOS-like input thresholds has been extended to the Ports 0, 1 and 5.

### ST10F276: XPICON (EB26h)

XREG

Reset Value: --00h

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	-	-	-	P5HIN	P5LIN	P1HIN	P1LIN	P0HIN	P0LIN
										RW	RW	RW	RW	RW	RW

Bit	Function	Reset Value
5	<b>P5HIN:</b> <i>Port 5 High Byte Input Level Selection</i> 0: Pins P5.15..8 switch on standard TTL input levels 1: Pins P5.15..8 switch on CMOS input levels	0
4	<b>P5LIN:</b> <i>Port 5 Low Byte Input Level Selection</i> 0: Pins P5.7..0 switch on standard TTL input levels 1: Pins P5.7..0 switch on CMOS input levels	0
3	<b>P1HIN:</b> <i>Port 1 High Byte Input Level Selection</i> 0: Pins P1.15..8 switch on standard TTL input levels 1: Pins P1.15..8 switch on CMOS input levels	0
2	<b>P1LIN:</b> <i>Port 1 Low Byte Input Level Selection</i> 0: Pins P1.7..0 switch on standard TTL input levels 1: Pins P1.7..0 switch on CMOS input levels	0
1	<b>P0HIN:</b> <i>Port 0 High Byte Input Level Selection</i> 0: Pins P0.15..8 switch on standard TTL input levels 1: Pins P0.15..8 switch on CMOS input levels	0
0	<b>P0LIN:</b> <i>Port 0 Low Byte Input Level Selection</i> 0: Pins P0.7..0 switch on standard TTL input levels 1: Pins P0.7..0 switch on CMOS input levels	0

### 4.4.1 Hardware impact

None.

### 4.4.2 Software impact

None.

## 4.5 XMISC register

### ST10F276: XMISC (EB46h)

XREG

Reset Value: 0000h

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	-	-	-	-	-	VREG OFF	CAN CK2	CAN PAR	ADC MUX
-	-	-	-	-	-	-	-	-	-	-	-	RW	RW	RW	RW

Bit	Function
15:4	Reserved
3	<b>VREGOFF:</b> <i>Main Voltage Regulator disable in Power-Down mode</i> 0: On-chip Main Regulator is held active when Power-Down mode is entered 1: On-chip Main Regulator is turned off when Power-Down mode is entered
2	<b>CANCK2:</b> <i>CAN Clock divider by 2 disable</i> 0: Clock provided to CAN modules is CPU clock divided by 2 (mandatory when $F_{CPU}$ is higher than 40MHz) 1: Clock provided to CAN modules is directly CPU clock
1	<b>CANPAR:</b> <i>CAN Parallel Mode Selection</i> 0: CAN2 is mapped on P4.4/P4.7, while CAN1 is mapped on P4.5/P4.6 1: CAN1 and CAN2 are mapped in parallel on P4.5/P4.6. This is effective only if both CAN1 and CAN2 are enabled through setting of bits CAN1EN and CAN2EN in XPERCON register. If CAN1 is disabled, CAN2 remains on P4.4/P4.7 even if bit CANPAR is set.
0	<b>ADCMUX:</b> <i>Port1L ADC Channels Enable</i> 0: Analog inputs on port P5.y can be converted (default configuration) 1: Analog inputs on port P1.z can be converted. Only 8 channels can be managed

### 4.5.1 Hardware impact

None.

### 4.5.2 Software impact

None.

## 4.6 Emulation dedicated registers

A set of additional four registers are implemented for emulation purpose only. Similarly to XPEREMU, they are write only registers.

XEMU0 (00'EB76h)

XEMU1 (00'EB78h)

XEMU2 (00'EB7Ah)

XEMU3 (00'EB7Ch)

These registers are used by emulators. They have no user action on the ST10F276.

#### **4.6.1 Hardware impact**

None.

#### **4.6.2 Software impact**

None.

## 5 Electrical characteristics

### 5.1 DC characteristics

#### 5.1.1 Absolute maximum ratings

They are the same.

#### 5.1.2 DC characteristics

##### Overview of the DC characteristics

The pads of the ST10F276 have been redesigned according to the new technology and therefore the characteristics are different. Users should verify the DC characteristics.

The table below lists the parameters that might have the biggest impact.

Parameter	Symbol	ST10F168 Limit Values		ST10F276 Limit Values		Unit
		min.	max.	min.	max.	
Input low voltage	VIL SR VILSSR	-0.5 -0.5	0.2 VDD - 0.1 2.0, (special threshold)	-0.3 -0.3	0.8 0.3 VDD	V
Input low voltage (RSTIN, EA, NMI, and RPD)	VIL1 SR	N.A.	N.A.	-0.3	0.3 VDD	V
Input low voltage (XTAL1 and XTAL3)	VIL2 SR			-0.3	0.3 VDD	V
Input high voltage	VIH SR VIHSSR	0.2 VDD + 0.9 0.8 VDD - 0.2	VDD + 0.5 VDD + 0.5, (special threshold)	2.0 0.7 VDD	VDD + 0.3 VDD + 0.3	V
Input high voltage (RSTIN, EA, NMI, and RPD)	VIH1 SR	0.6 VDD	VDD + 0.5, (special threshold)	0.7 VDD	VDD + 0.3	V
Input high voltage XTAL1	VIH2SR	0.7 VDD	VDD + 0.5	0.7 VDD	VDD + 0.3	V
Input Hysteresis	HYS	N.A. 300, special threshold	-	400 750	-	mV
Input Hysteresis RSTIN, EA, NMI	VHYS1CC			800		mV
Output low voltage	VOL CC	PORT0, PORT1, Port 4, ALE, RD, WR, BHE, CLKOUT, RSTOUT	0.45 / I <sub>ol</sub> = 2.4mA	PORT6, ALE, CLKOUT, WR, READY, BHE, RD, RSTOUT, RSTIN	0.4 / I <sub>ol</sub> = 8mA 0.05 / I <sub>ol</sub> = 1mA	V
Output low voltage (all other outputs)	VOL1CC	—	0.45 / I <sub>ol</sub> = 1.6mA	—	0.4 / I <sub>ol</sub> = 4 mA 0.05 / I <sub>ol</sub> = 0.5 mA	V
Output high voltage	VOHCC	0.9VDD / I <sub>oh</sub> = -0.5 mA 2.4 / I <sub>oh</sub> = -2.4 mA	PORT0, PORT1, Port 4, ALE, RD, WR, BHE, CLKOUT, RSTOUT	VDD - 0.8 / I <sub>oh</sub> = -8 mA VDD - 0.08 / I <sub>oh</sub> = -1 mA	PORT6, ALE, CLKOUT, WR, READY, BHE, RD, RSTOUT, RSTIN	V
Output high voltage (all other outputs)	VOH1CC	0.9VDD / I <sub>oh</sub> = -0.25 mA 2.4 / I <sub>oh</sub> = -1.6 mA	—	VDD - 0.8 / I <sub>oh</sub> = -4 mA VDD - 0.08 / I <sub>oh</sub> = -0.5 mA	—	V

Parameter	Symbol	ST10F168 Limit Values		ST10F276 Limit Values		Unit
		min.	max.	min.	max.	
Input leakage current (Port 5)	IOZ1CC	–	$\pm 500 / 0 \text{ V} < \text{VIN} < \text{VDD}$	–	$\pm 200$	nA
Input leakage current (all other)	IOZ2CC	–	$\pm 1 / 0 \text{ V} < \text{VIN} < \text{VDD}$	–	$\pm 0.5$	uA
Input leakage current (P2.0)	IOZ3CC	–	-	–	-0.5 +1	uA
Input leakage current (RPD)	IOZ4CC	–	-	–	$\pm 3$	uA
Overload current (P2.0)	IOV2CC	–	-	–	-1 +5	mA

## 6 References

The following documents were used to write this application note:

- ST10F168 Datasheet
- ST10F276 Datasheet
- AN1313 Application Note "Porting an application from the ST10F168 to the ST10F269"

## 7 Revision history

**Table 7. Document revision history**

Date	Revision	Changes
3-Jul-2006	1	Initial release.



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